

Technical Data Sheet

1.6mm round Subminiature Side Looking Infrared LED

IR26-51C/L110/TR8

Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel.
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

- IR26-51C/L110/TR8 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens. The device is spectrally matched with silicon photodiode and phototransistor.

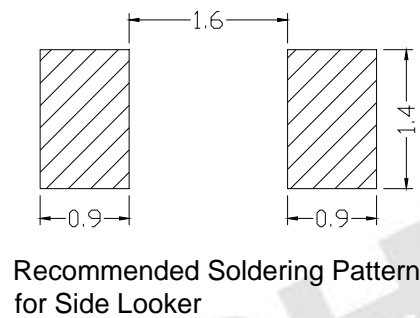
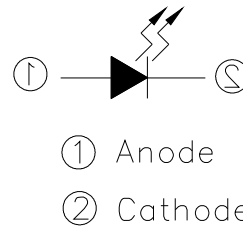
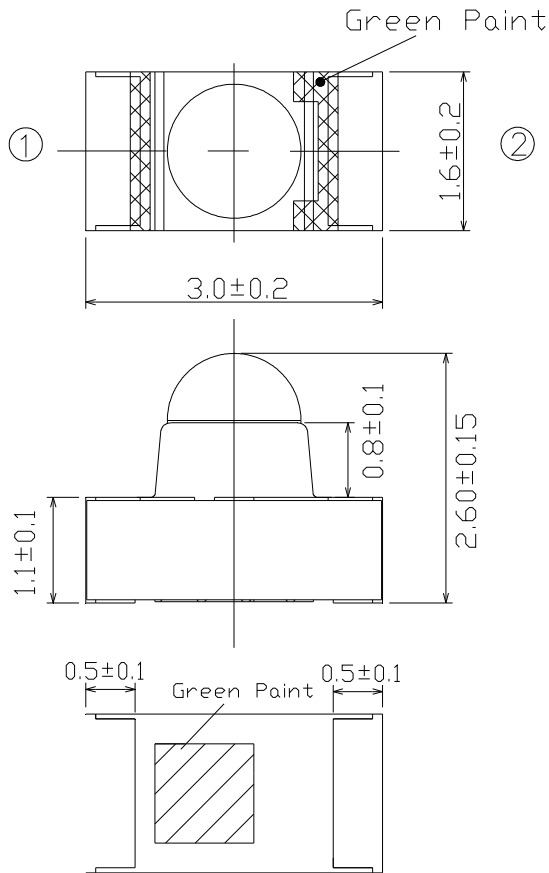
Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

Device Selection Guide

| Device No. | Chip Material | Lens Color |
|-------------------|---------------|-------------|
| IR26-51C/L110/TR8 | GaAlAs | Water Clear |

Package Dimensions



- Notes:** 1.All dimensions are in millimeters
2.Tolerances unless dimensions ± 0.1 mm

Absolute Maximum Ratings (Ta=25)

| Parameter | Symbol | Rating | Unit |
|---|-----------|------------|------|
| Continuous Forward Current | I_F | 65 | mA |
| Reverse Voltage | V_R | 5 | V |
| Operating Temperature | T_{opr} | -25 ~ +85 | |
| Storage Temperature | T_{stg} | -40 ~ +100 | |
| Soldering Temperature *1 | T_{sol} | 260 | |
| Power Dissipation at(or below) 25 Free Air Temperature | P_d | 130 | mW |

Notes: *1:Soldering time 5 seconds.

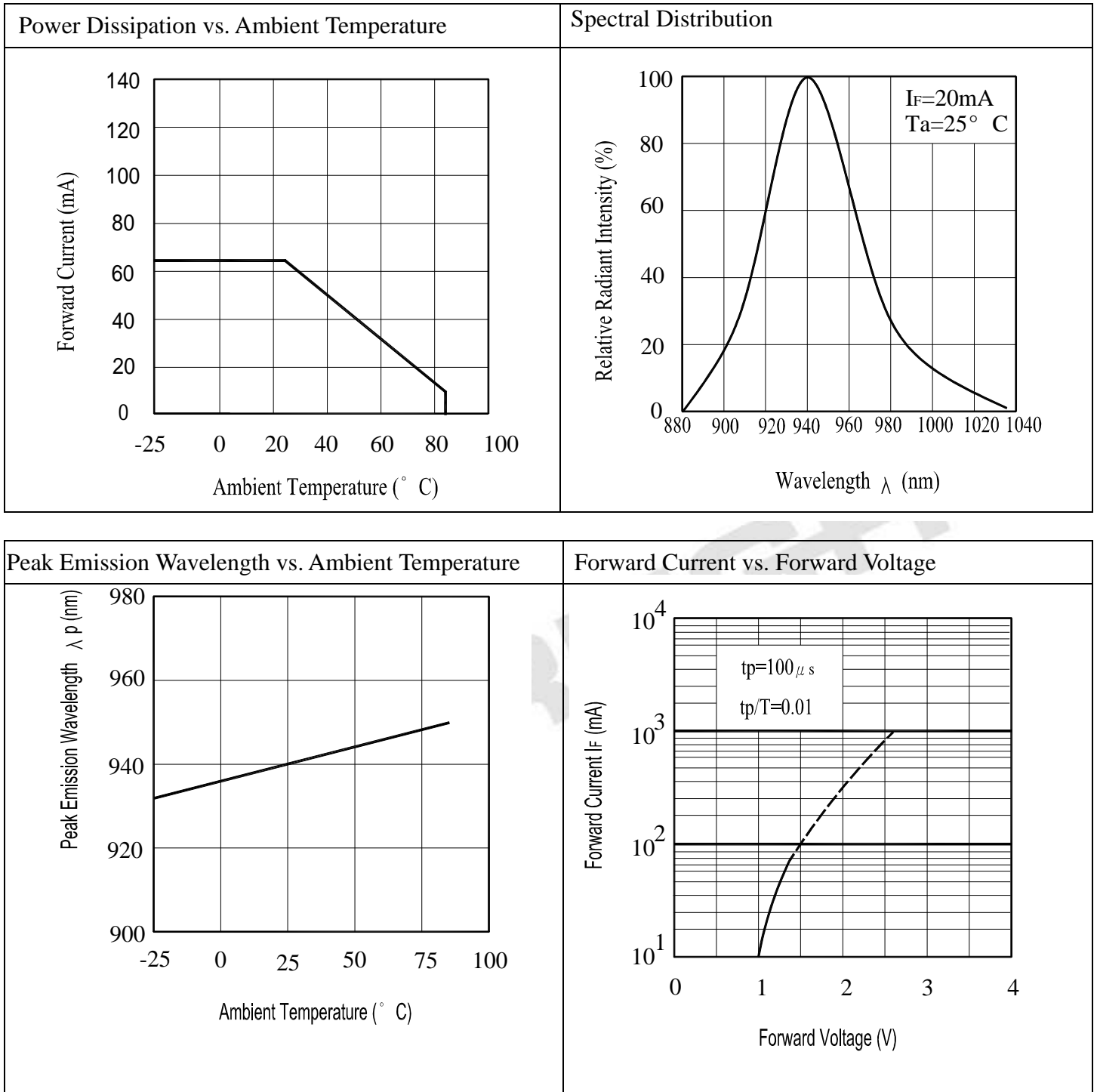
Electro-Optical Characteristics (Ta=25)

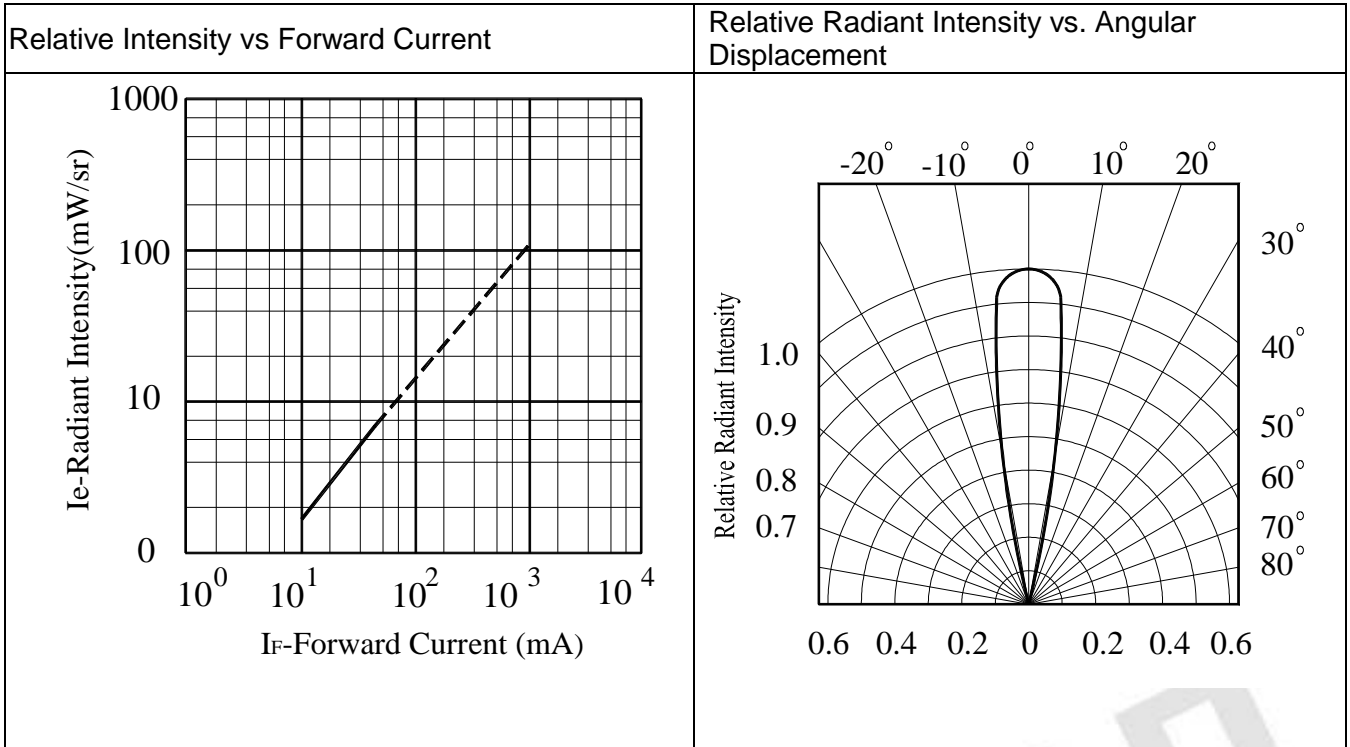
| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|--------------------|-------------------|------|------|------|--------|---|
| Radiant Intensity | I _e | 2.0 | 4.5 | -- | mW /sr | I _F =20mA |
| | | -- | 15 | -- | | I _F =100mA Pulse Width 100 μ s ,Duty 1% |
| Peak Wavelength | λ | -- | 940 | -- | nm | I _F =20mA |
| Spectral Bandwidth | | -- | 45 | -- | nm | I _F =20mA |
| Forward Voltage | V _F | -- | 1.2 | 1.5 | V | I _F =20mA |
| | | -- | 1.5 | 1.8 | | I _F =100mA Pulse Width 100 μ s ,Duty 1% |
| | | -- | 2.6 | 4.0 | | I _F =1A Pulse Width 100 μ s ,Duty 1 |
| Reverse Current | I _R | -- | -- | 10 | μ A | V _R =5V |
| View Angle | 2θ _{1/2} | -- | 20 | -- | deg | I _F =20mA |

Rankings

| Rank | Test Condition | Min | Max | Unit |
|------|----------------------|-----|------|-------|
| H | I _F =20mA | 2.0 | 3.5 | mW/sr |
| J | | 3.0 | 4.5 | |
| K | | 4.0 | 6.0 | |
| L | | 5.0 | 7.5 | |
| M | | 6.0 | 9.0 | |
| N | | 7.0 | 10.5 | |

Typical Electrical/Optical/Characteristics Curves for IR





EVERLIGHT

● **Precautions For Use**

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30 or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30 or less and 70%RH or less.

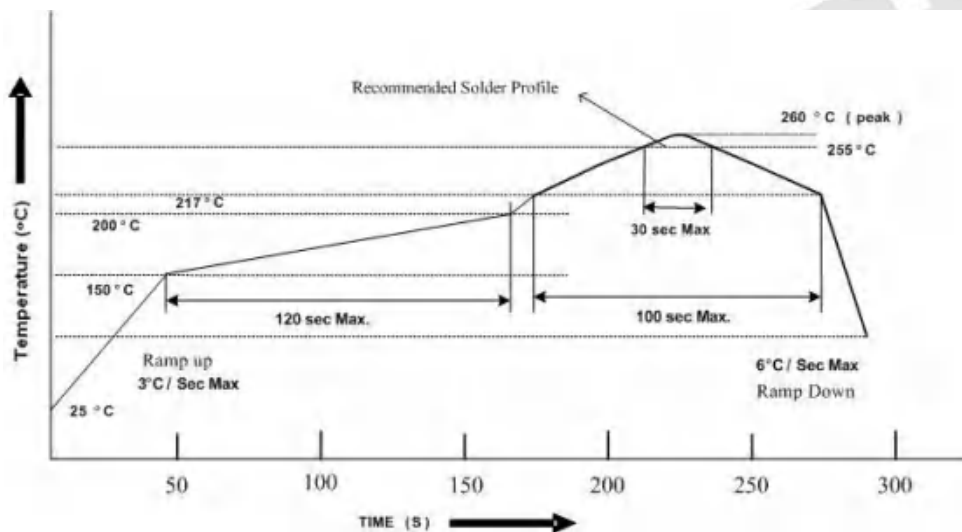
2.5 The LEDs should be used within 168 hours (7 days) after opening the package

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5 for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

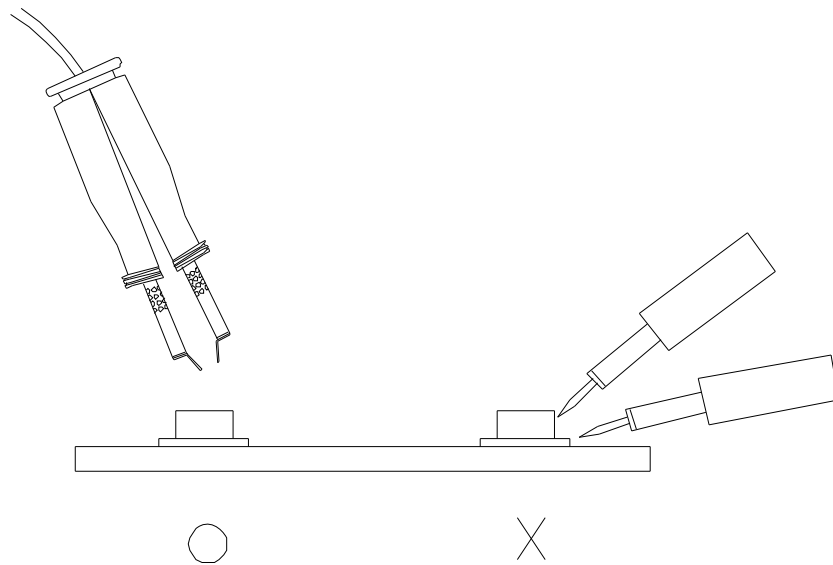
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

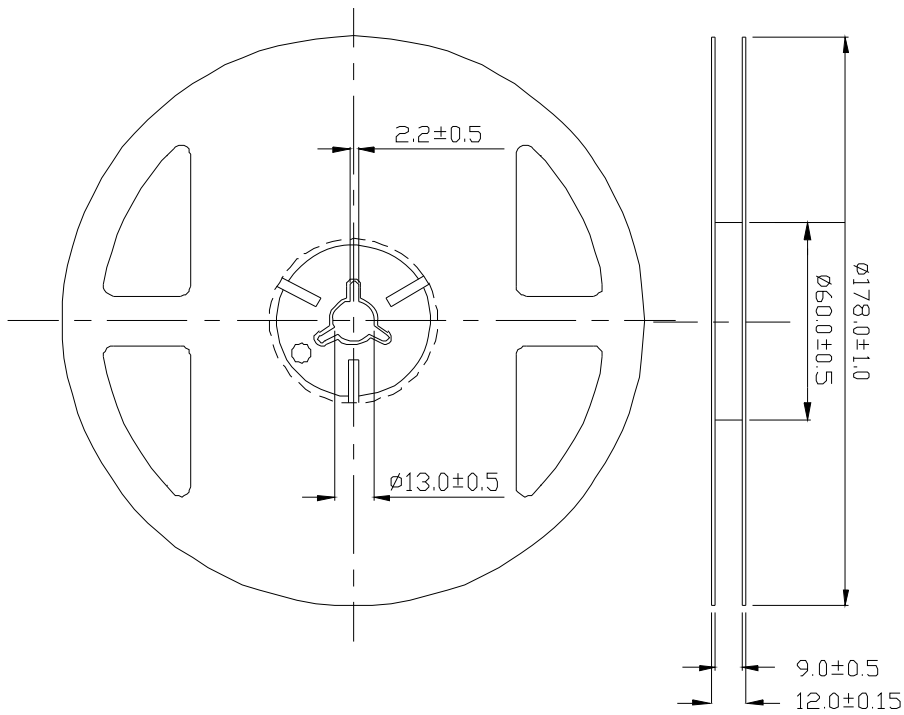
Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

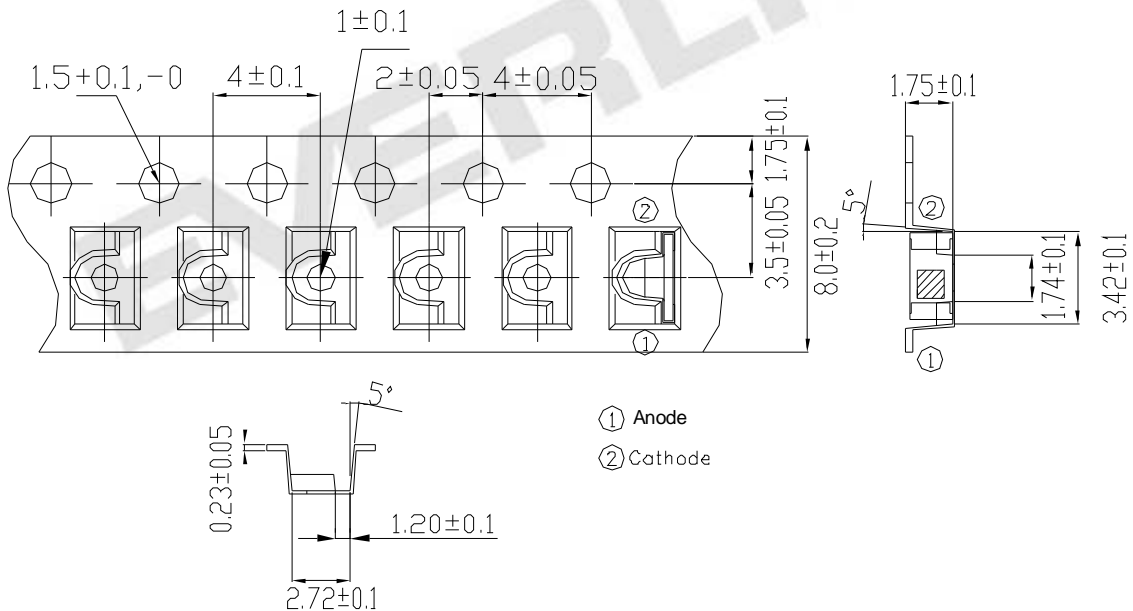


Package Dimensions



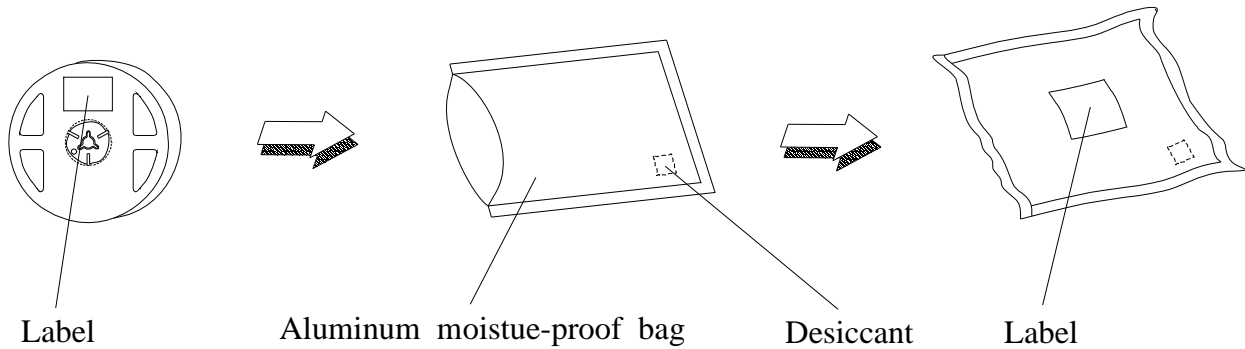
Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

2. Carrier Tape Dimensions:(Quantity: 1500pcs/reel)



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Packing Procedure



Label Form Specification

The label form includes the following fields and symbols:

- RoHS symbol (Pb)
- EVERLIGHT logo
- CPN: XXXXXXXXXXXXXXXX
- P/N: XXXXXXXXXXXXXXXX
- XXXXXXXXXXXXXXXXXX
- RoHS symbol
- QTY: XXX
- CAT: XXX
- HUE: XXX
- REF: XXX
- LOT NO: XXXXXXXXXXXX
- Reference: XXXXXXXX

CPN: Customer's Production Number
P/N : Production Number
QTY: Packing Quantity
CAT: Ranks
HUE: Peak Wavelength
REF: Reference
LOT No: Lot Number
MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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